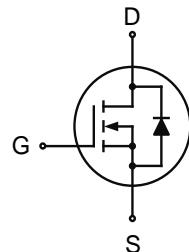


Features

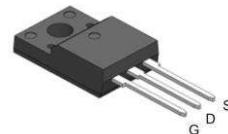
- 650V,14A
 $R_{DS(on)} < 310\text{m}\Omega @ V_{GS}=10\text{V}$ TYP:260m Ω
- New revolutionary high voltage technology
- Ultra Low Gate charge
- 100% avalanche tested



Schematic Diagram

Applications

- Low RDS(on) & FOM
- Low gate charge
- Provide superior switching
- Withstand extreme dv/dt rate
- Higher avalanche energy
- AC/DC



TO-220F

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
A65R310FM	APA65R310FM	TO-220F	-	-	1000

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	650	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current ($T_c = 25^\circ\text{C}$)	I_D	14	A
Continuous Drain Current ($T_c = 100^\circ\text{C}$)	I_D	8.8	A
Pulsed Drain Current	I_{DM}	56	A
Reverse diode dv/dt ⁽²⁾	dv/dt	15	V/ns
MOSFET dv/dt ruggedness ⁽³⁾	dv/dt	50	V/ns
Single Pulsed Avalanche Energy (1)	E_{AS}	593	mJ
Drain Power Dissipation	P_D	35.7	W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	3.5	°C/W
Thermal Resistance- Junction to Ambient	$R_{\theta JA}$	62.5	°C/W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55~+150	°C
Maximum Lead temperature for soldering Purpose	T_L	300	°C

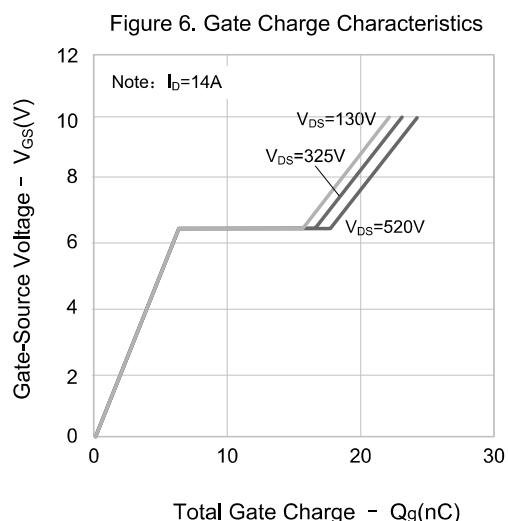
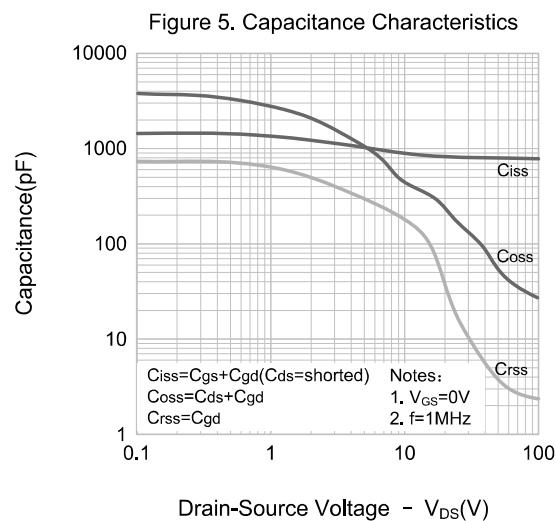
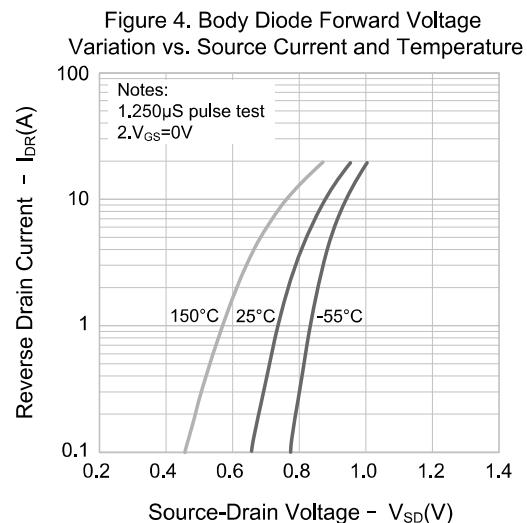
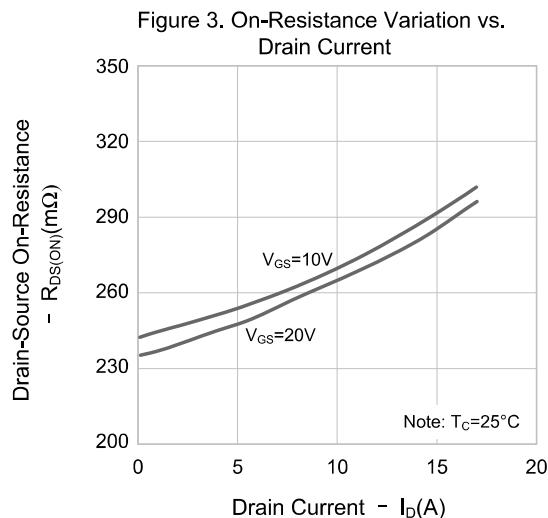
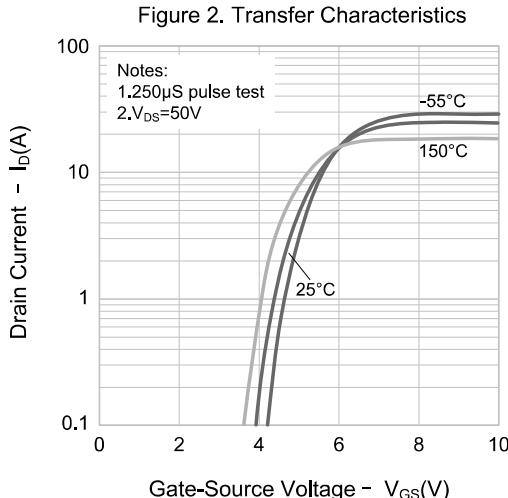
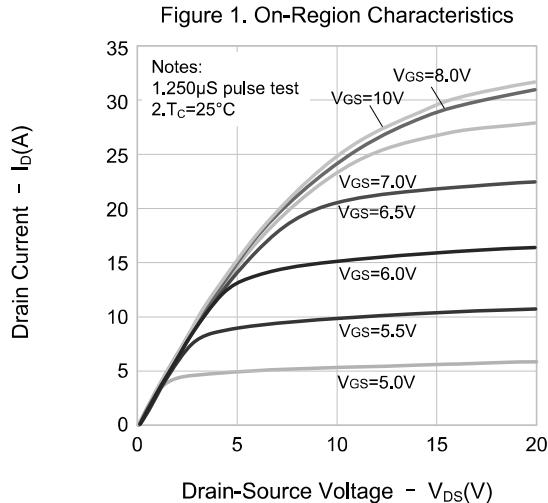
MOSFET ELECTRICAL CHARACTERISTICS($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	650	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}} = 650\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	1	μA
Gate-body leakage current	I_{GSS}	$V_{\text{GS}} = \pm 30\text{V}, V_{\text{DS}} = 0\text{V}$	-	-	± 100	nA
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.0	-	4.0	V
Drain-source on-resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 7\text{A}$	-	260	310	$\text{m}\Omega$
Dynamic characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0\text{MHz}$	-	802	-	pF
Output Capacitance	C_{oss}		-	45	-	
Reverse Transfer Capacitance	C_{rss}		-	2.2	-	
Switching characteristics						
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 325\text{V}, I_D = 14\text{A}, R_G = 25\Omega, V_G = 10\text{V}$	-	13	-	ns
Turn-on rise time	t_r		-	37	-	
Turn-off delay time	$t_{\text{d}(\text{off})}$		-	59	-	
Turn-off fall time	t_f		-	32	-	
Total Gate Charge	Q_g	$V_{\text{DS}} = 520\text{V}, I_D = 14\text{A}, V_{\text{GS}} = 10\text{V}$	-	24	-	nC
Gate-Source Charge	Q_{gs}		-	6.5	-	
Gate-Drain Charge	Q_{gd}		-	11	-	
Source-Drain Diode characteristics						
Diode Forward voltage	V_{SD}	$T_c = 25^\circ\text{C}, V_{\text{GS}} = 0\text{V}, I_S = 14\text{A}$	-	-	1.4	V
Diode Forward current	I_S	$T_c = 25^\circ\text{C}$	-	-	14	A
Body Diode Reverse Recovery Time	trr	$T_c = 25^\circ\text{C}, IF = 14\text{A}, di/dt = 100\text{A/us}$		367		ns
Body Diode Reverse Recovery Charge	Q_{rr}	$T_c = 25^\circ\text{C}, IF = 14\text{A}, di/dt = 100\text{A/us}$		4.7		uc

Notes:

1. $L = 79\text{mH}, I_{AS} = 4.8\text{A}, V_{DD} = 100\text{V}, RG = 25\Omega$, starting temperature $T_J = 25^\circ\text{C}$;
2. $V_{DS} = 0 \sim 400\text{V}, ISD \leq 14\text{A}, TJ = 25^\circ\text{C}$;
3. $V_{DS} = 0 \sim 480\text{V}$;
4. Pulse test: Pulse width $\leq 300\text{us}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

Typical Performance Characteristics



Typical Performance Characteristics

Figure 7. Breakdown Voltage Variation
vs. Temperature

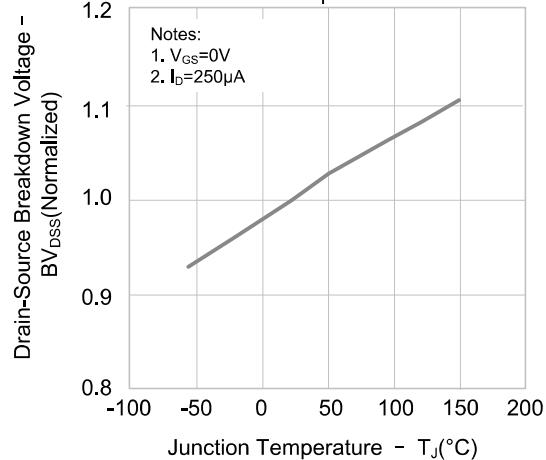


Figure 8. On-resistance Variation
vs. Temperature

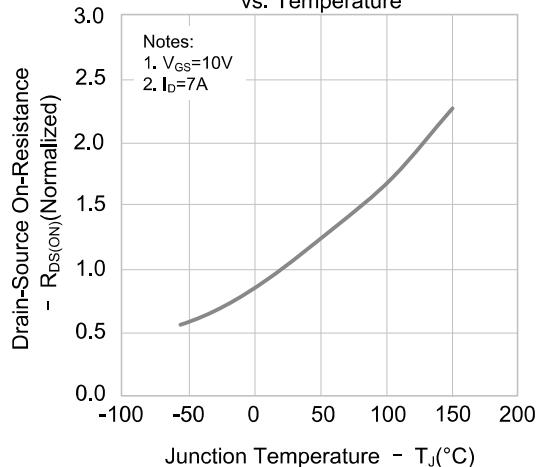
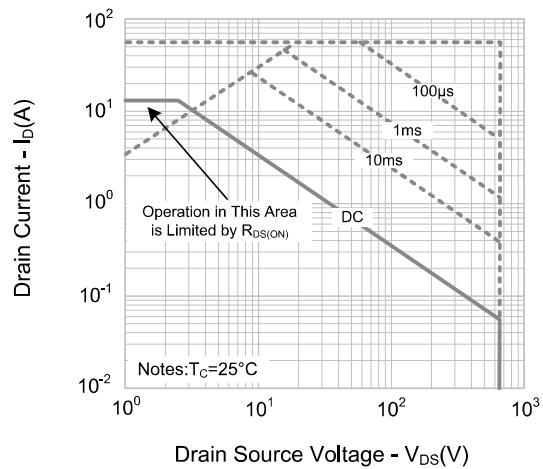
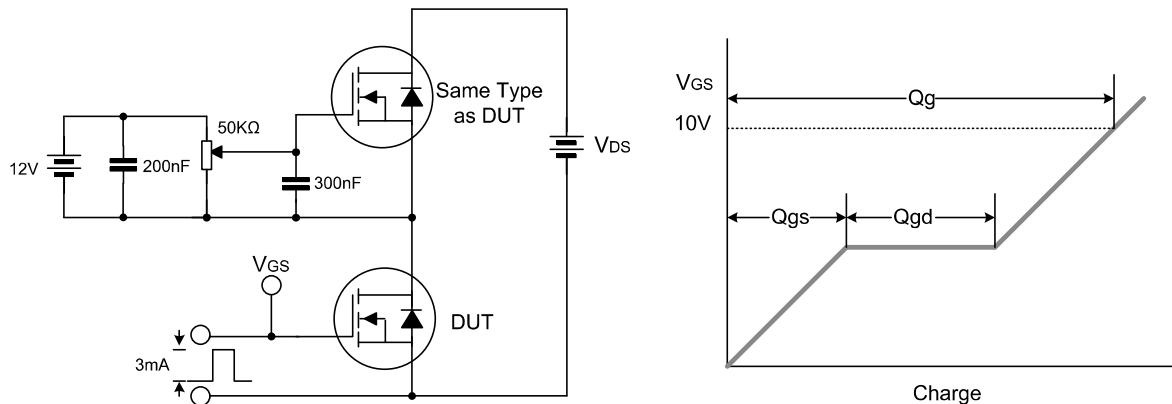


Figure 9. Max. Safe Operating Area

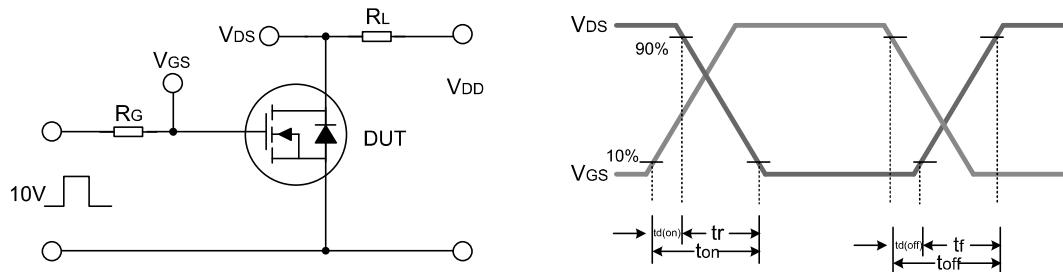


Test circuits

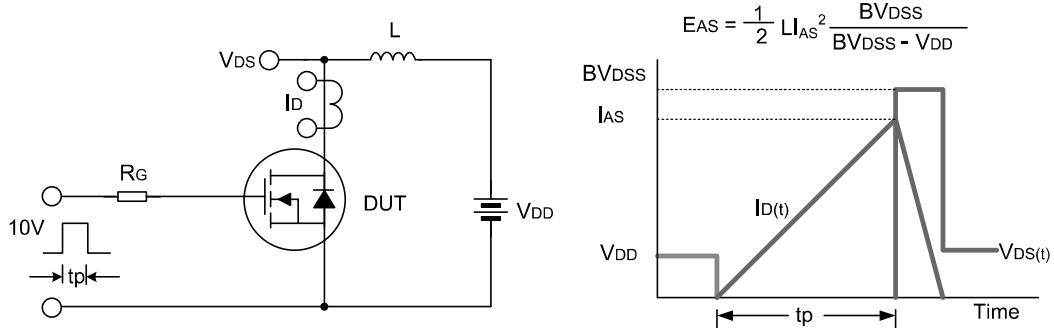
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching Test Circuit & Waveform



Package Dimensions

TO-220F		Unit: mm		
SYMBOL	MIN	NOM	MAX	
A	4.42	4.70	5.02	
A1	2.30	2.54	2.80	
A3	2.50	2.76	3.10	
b	0.70	0.80	0.90	
b2	—	—	1.47	
c	0.35	0.50	0.65	
D	15.25	15.87	16.25	
D1	15.30	15.75	16.30	
D2	9.30	9.80	10.30	
E	9.73	10.16	10.36	
e	2.54BCS			
H1	6.40	6.68	7.00	
L	12.48	12.98	13.48	
L1	/	/	3.50	
ØP	3.00	3.18	3.40	
Q	3.05	3.30	3.55	